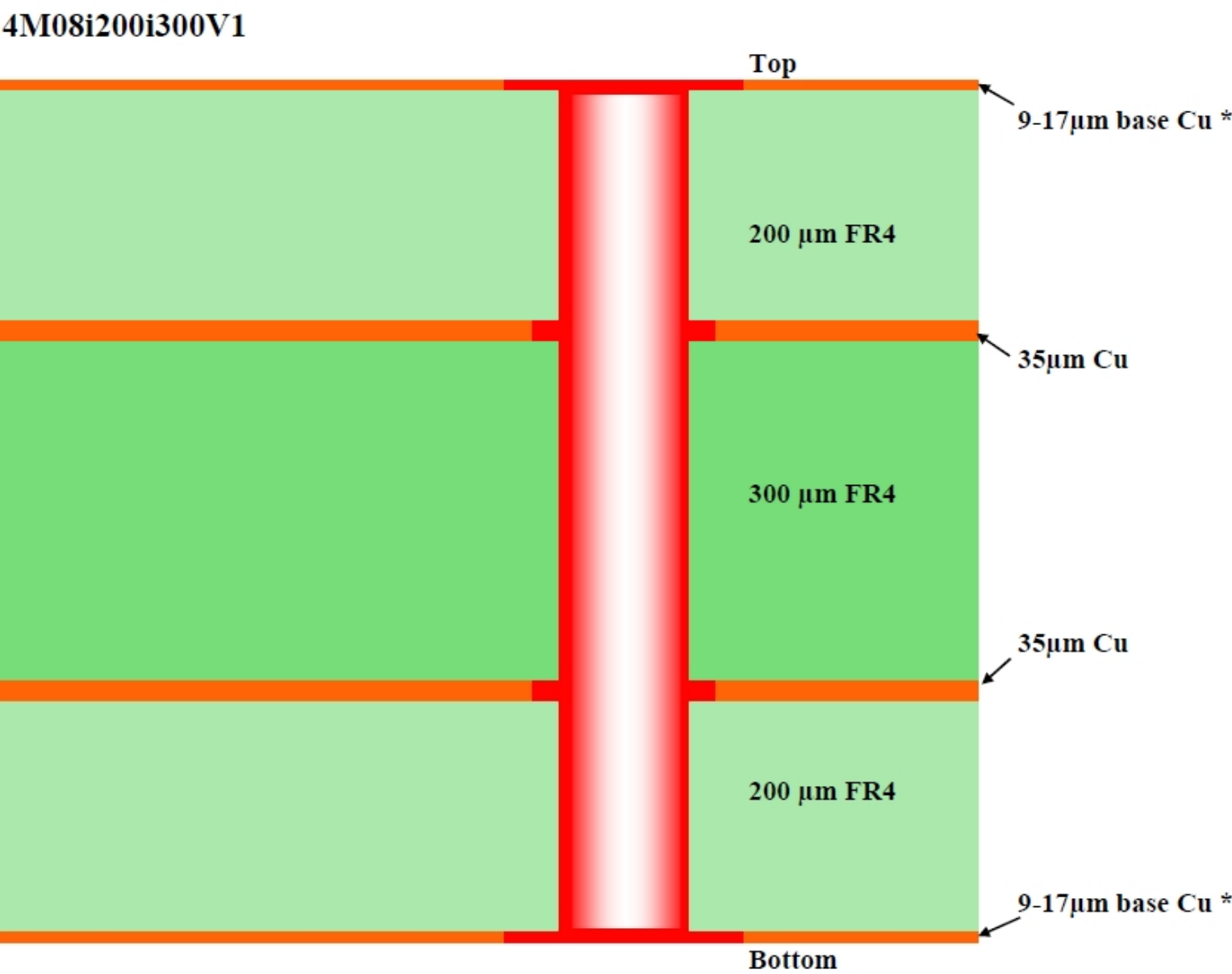


WMI

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PCB-Stackup



Tolerance: For each listed base material (Prepreg, Core) acc. to IPC-4101 Class C/M

* Final Copper-thickness (base Cu + plating) acc. to IPC-6012 Class II

The PCB-thickness (over all dimension) is a result of the addition of the multilayer thickness plus copper plating and plus soldermask = **0.9 mm ± 10%**

Legend:

Functionblock

Line Style = Dot

Source2Target-SignalName < 2 IN Signal (crossref-xxx-IN.1)

Source2Target-SignalName > 2 OUT Signal (crossref-xxx-OUT.1)

Host2Slave-SignalName < 2 Bidirectional (crossref-xxx.1)

EMC-Shielding

Line Style = Big Dash

A? GND

Comments and notes

Line Style = Phantom

LP? Solder Pad

TP? Test Point

Spark Gap

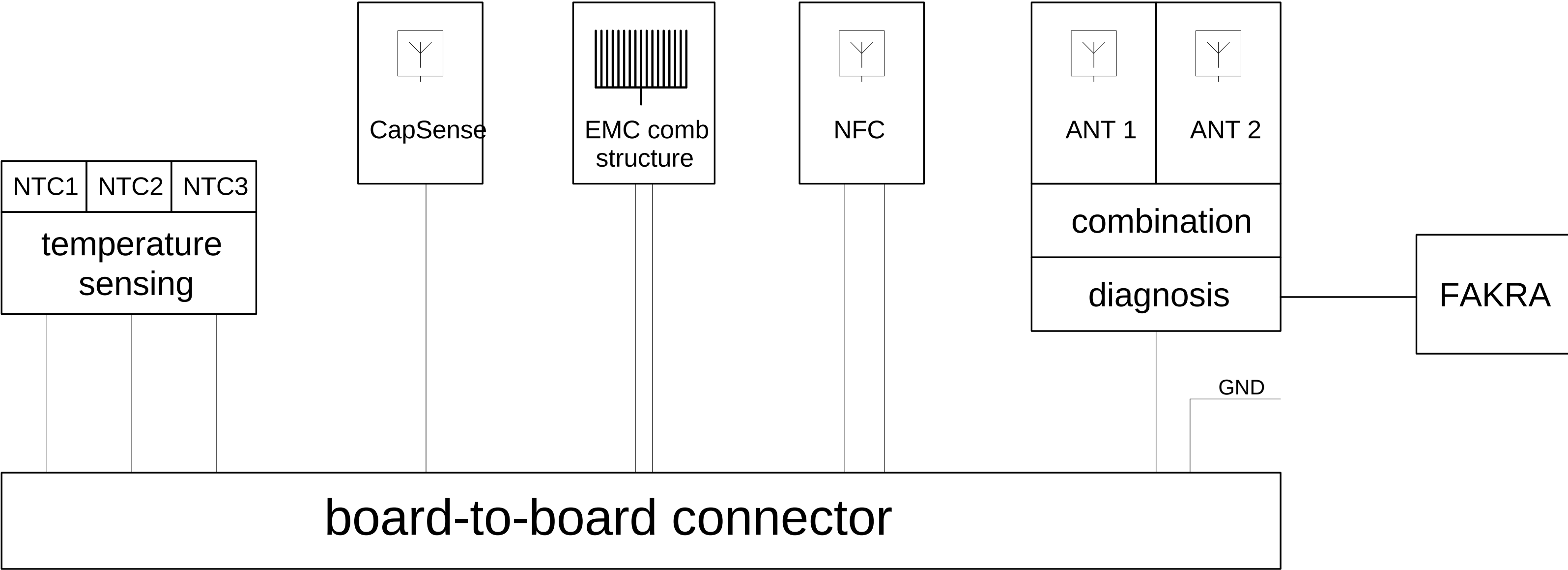
Bridge

Diff pair

Trace Impedance

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Substitute for:				Date	Name	Schematic V1240-904/LP1450-4 WMI02 ANT w/o GSM DAG		
				Drawn	21.03.17			
				Check.				
				Viewed				
						2189-240-904-00		
a	AEM7524	27.06.17	Piper					
	Revision	Date	Name					

Block Diagram



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Substitute for:						Printed: 27-06-2017 / 09:38		2 of 3	
☐				Date	Name	Schematic V1240-904/LP1450-4 WMI02 ANT w/o GSM DAG			
☐				Drawn	21.03.17 Bock				
☐				Check.	see page 1				
☐				Viewed	see page 1				
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☒	AEM7524	27.06.17	Piper			2189-240-904-00			
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2189-240-904-00

